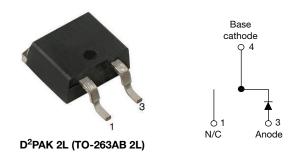
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Hyperfast Rectifier, 30 A FRED Pt[®] G5



LINKS TO ADDITIONAL RESOURCES



SHA

PRIMARY CHARACTERISTICS								
I _{F(AV)}	30 A							
V _R	600 V							
V _F at I _F at 125 °C	1.15 V							
t _{rr} (typ.)	25 ns							
T _J max.	175 °C							
Package	2L D ² PAK (2L TO-263AB)							
Circuit configuration	Single							

FEATURES

· Best in class forward voltage drop and switching losses trade off



FREE

- · Optimized for high speed operation
 - COMPLIANT HALOGEN
- 175 °C maximum operating junction temperature
- Polyimide passivation
- AEC-Q101 qualified, meets JESD 201 class 1A whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION / APPLICATIONS

Featuring a unique combination of low conduction and switching losses, this rectifier is the right choice for soft switched and resonant converters, as well as medium frequency hard switching converters. This device is specifically designed to improve efficiency of high speed LLC output rectification stages of EV / HEV battery charging stations and high frequency stages of UPS applications.

MECHANICAL DATA

Case: D²PAK 2L (TO-263AB 2L)

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RATINGS										
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS						
Repetitive peak reverse voltage	V _{RRM}		600	V						
Average rectified forward current	I _{F(AV)}	T _C = 113 °C, D = 0.50	30	А						
Repetitive peak forward current	I _{FRM}	T _C = 113 °C, D = 0.50, f = 20 kHz	60							
Non-repetitive peak surge current	I _{FSM}	T_{C} = 25 °C, t_{p} = 10 ms, sine wave	330							
Operating junction and storage temperature	T _J , T _{Stg}		-55 to +175	°C						

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	600	-	-				
Forward voltage	VF	I _F = 30 A	-	1.3	1.6	V			
Forward voltage	۷F	I _F = 30 A, T _J = 125 °C	-	1.15	-				
Deverse leakage eurrent	1	V _R = V _R rated	-	-	20				
Reverse leakage current	IR	$T_J = 125 \text{ °C}, V_R = V_R \text{ rated}$	-	-	500	μA			
Junction capacitance	CT	V _R = 200 V	-	36	-	pF			
Series inductance	L _S	Measured to lead 5 mm from package body	-	8	-	nH			





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DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25 \text{ °C}$ unless otherwise specified)										
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS			
		I _F = 1.0 A,dI _F /dt =	100 A/µs, V _R = 30 V	-	25	-				
Reverse recovery time	t _{rr}	T _J = 25 °C		-	41	-	ns			
		T _J = 125 °C		-	58	-				
Peak recovery current	1	T _J = 25 °C	I _F = 20 A dI _F /dt = 1000 A/μs	-	19	-	A			
	I _{RRM}	T _J = 125 °C	$V_{\rm R} = 400 \text{ V}$	-	32	-				
	0	T _J = 25 °C		-	419	-	nC			
Reverse recovery charge	Q _{rr}	T _J = 125 °C		-	1176	-				
	+	T _J = 25 °C		-	46	-	ns			
Reverse recovery time	t _{rr}	T _J = 125 °C		-	65	-				
Poak racovany ourrant	1	T _J = 25 °C	I _F = 30 A dI _F /dt = 1000 A/μs	-	21	-	- A			
Peak recovery current	I _{RRM}	T _J = 125 °C	$V_{\rm R} = 400 \text{V}$	-	36	-				
	0	T _J = 25 °C		-	550	-				
Reverse recovery charge	Q _{rr}	T _J = 125 °C		-	1560	-	nC			

THERMAL - MECHANICAL SPECIFICATIONS										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Thermal resistance, junction-to-case	R _{thJC}		-	-	1.3	°C/W				
Weight			-	2.0	-	g				
weight			-	0.07	-	oz.				
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C				
Marking device		Case style 2L D ² PAK (2L TO-263AB	E5TH3006SH							



VS-E5TH3006S2LHM3

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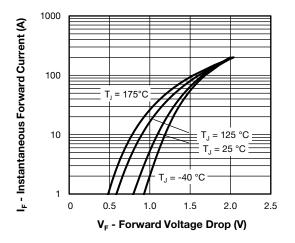


Fig. 1 - Forward Voltage Drop Characteristics, Per Leg

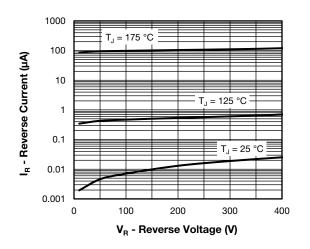


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage, Per Leg

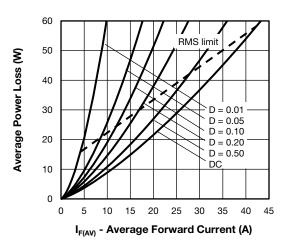


Fig. 5 - Forward Power Loss Characteristics, Per Leg

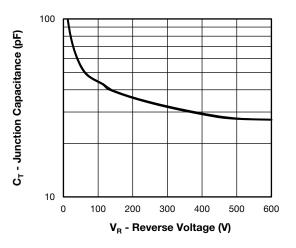


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage, Per Leg

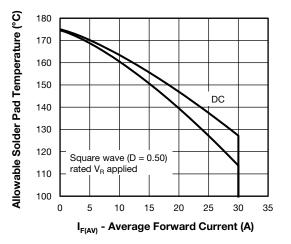


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current, Per Leg

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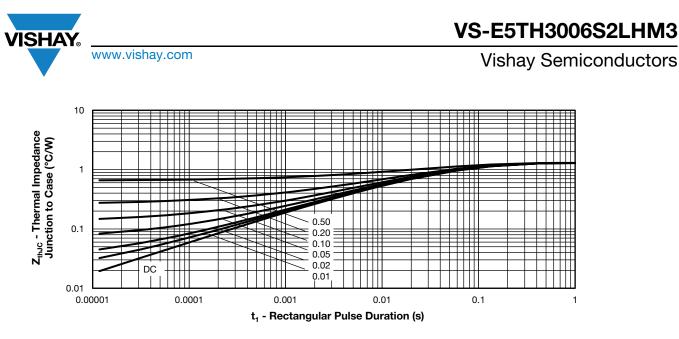


Fig. 6 - Transient Thermal Impedance, Junction to Case, Per Leg

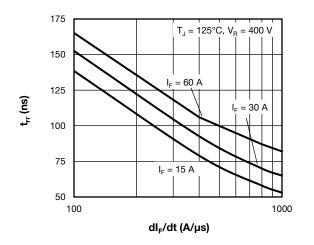


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt, Per Leg

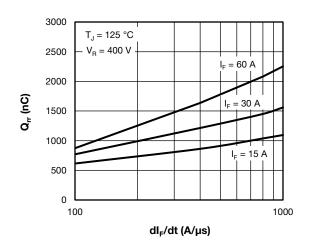


Fig. 8 - Typical Reverse Recovery Charge vs. dl_F/dt, Per Leg

45 T_J = 125 °C $I_{\rm F} = 60 \, {\rm A}$ 40 $V_{R} = 400 V$ 35 $I_{F} = 30 \text{ A}$ 30 **ا**_۳ (A) 25 20 = 15 A I_E 15 10 5 100 1000 dl_F/dt (A/µs)

Fig. 9 - Typical Reverse Recovery Current vs. dI_F/dt , Per Leg

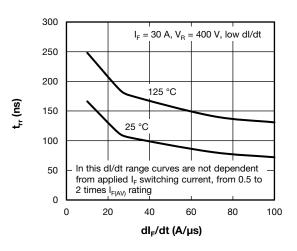


Fig. 10 - Typical Reverse Recovery Time vs. dl_F/dt, Per Leg

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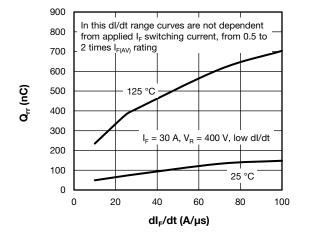


Fig. 11 - Typical Reverse Recovery Charge vs. dl_F/dt, Per Leg

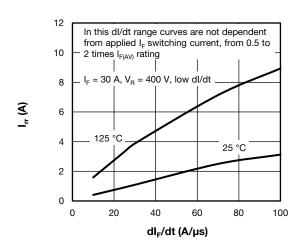


Fig. 12 - Typical Reverse Recovery Current vs. dl_F/dt, Per Leg

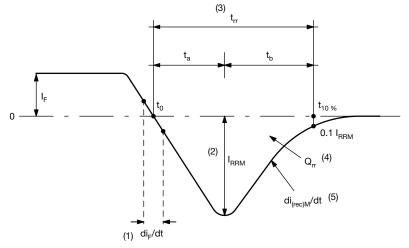


Fig. 13 - Reverse Recovery Waveform and Definitions

Notes

- $^{(1)}~di_{\text{F}}/dt$ rate of change of current through zero crossing
- $^{(2)}\ \ I_{RRM}$ peak reverse recovery current
- $^{(3)}$ t_{rr} reverse recovery time measured from t₀, crossing point of negative going I_F, to point t_{10%}, 0.1 I_{RRM}
- $^{(4)}~Q_{rr}$ area under curve defined by t_0 and $t_{10\ \%}$

$$Q_{rr} = \int_{t_0}^{t_{10\%}} I(t) dt$$

 $^{(5)}$ di_(rec)M/dt - peak rate of change of current during t_b portion of t_{rr}

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ORDERING INFORMATION TABLE

VS-

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Device code

(1	2	3	4	5	6	7	8	9	(10)	(11)
1 2 3 4	-	E = 5 = Pac	single o FRED g kage:	liode Jeneratio							
5 6 7 8	-	H = Cur Volt	hyperfa rent rati age rati	ast reco ng (30 =	= 30 A) = 600 V)	-					
9	-	● L If n	= tape a eeded c		l (left ori orientat			AK pack please	• /	factory	
11	-			ntal digi [.] Jen-free		complia	ant, and	termina	tion lea	d (Pb)-f	ree

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ORDERING INFORMATION (Example)								
PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION					
VS-E5TH3006S2LHM3	800	800	13" diameter reel					

LINKS TO RELATED DOCUMENTS						
Dimensions	www.vishay.com/doc?96683					
Part marking information	www.vishay.com/doc?96693					
Packaging information	www.vishay.com/doc?95032					
SPICE model	www.vishay.com/doc?96919					



SHAY

Outline Dimensions

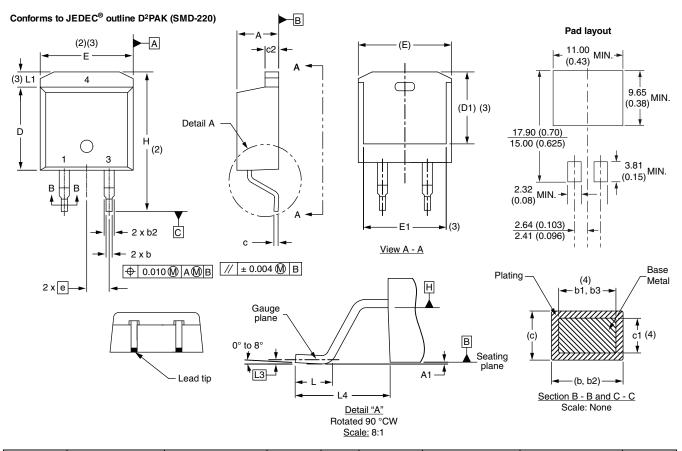


2L-D²PAK

DIMENSIONS in millimeters and inches

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SHAY



SYMBOL	MILLIMETERS		INCHES		NOTES		SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	STWDUL	MIN.	MAX.	MIN.	MAX.	NOTES	
А	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L3	0.25 BSC		0.010 BSC		
c2	1.14	1.65	0.045	0.065			L4	4.78	5.28	0.188	0.208	
D	8.51	9.65	0.335	0.380	2							

Notes

⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5 M-1994

⁽²⁾ Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
 ⁽²⁾ The outmost extremes of the plastic body

⁽³⁾ Thermal pad contour optional within dimension E, L1, D1 and E1

⁽⁴⁾ Dimension b1 and c1 apply to base metal only

⁽⁵⁾ Datum A and B to be determined at datum plane H

⁽⁶⁾ Controlling dimension: inch

⁽⁷⁾ Outline conforms to JEDEC[®] outline TO-263AB

Revision: 30-Nov-2020

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